

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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N-Channel IGBT With Low VF Switching Diode 600V, 30A, VCE(sat);1.4V



http://onsemi.com

Features

- IGBT VCE(sat)=1.4V typ. (IC=30A, VGE=15V)
- IGBT IC=100A (Tc=25°C)
- IGBT tf=80ns typ.
- Low switching loss in higher frequency applications
- Maximum junction temperature Tj=175°C
- Diode V_F=1.7V typ. (I_F=30A)
- Diode t_{rr} =70ns typ.
- 5µs short circuit capability
- Pb-free, Halogen-free and RoHS Compliance

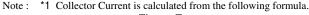
Applications

• Power factor correction of white goods appliance

Specifications

Absolute Maximum Ratings at Ta = 25°C, Unless otherwise specified

Paramete	Symbol	Value	Unit	
Collector to Emitter Voltage		VCES	V	
Gate to Emitter Voltage	V _{GES}	±20	V	
Collector Current (DC)	@Tc=25°C *2	11	100	Α
Limited by Tjmax	@Tc=100°C *2	IC *1	30	Α
Pulsed collector current,	OT 10000 t2			Α
tp=100ms limited by Tjmax	@Tc=100°C *2	lCpulse	60	
Pulsed collector current,	I _{Cpeak}	000	٨	
tp=1ms limited by Tjmax		232	Α	
Diode Average Output Curr	ent	IO	30	Α
Power Dissipation	_	205		
Tc=25°C (Our ideal heat dissi	PD	225	W	
Junction Temperature	Tj	175	°C	
Storage Temperature	Tstg	–55 to +175	°C	

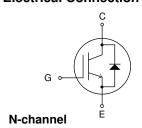


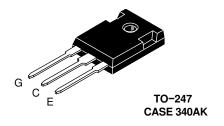
$$I_{C}(Tc) = \frac{Tjmax - Tc}{R_{th}(j-c) \times V_{CE}(sat) (I_{C}(Tc))}$$

*2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.

Electrical Connection





Marking



Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

Electrical Characteristics at Ta = 25°C, Unless otherwise specified

D	O. mada ad	Conditions		Value			11.2
Parameter	Symbol			min	typ	max	Unit
Collector to Emitter Breakdown Voltage	V(BR)CES	I _C =500μA, V _{GE} =0V		600			٧
0.11		V _{CE} =600V, V _{GE} =0V T _C =25°C T _C =150°C	Tc=25°C			10	μΑ
Collector to Emitter Cut off Current	ICES				1	mA	
Gate to Emitter Leakage Current	IGES	V _{GE} =±20V, V _{CE} =0V				±100	nA
Gate to Emitter Threshold Voltage	V _{GE} (th)	V _{CE} =20V, I _C =250μA		4.5		6.5	٧
	V _{CE} (sat)	V _{GE} =15V, I _C =30A	Tc=25°C		1.4	1.6	V
Collector to Emitter Saturation Voltage			Tc=150°C		1.7		٧
		V _{GE} =15V, I _C =50A	Tc=25°C		1.65		V
Diode Forward Voltage	VF	IF=30A			1.7		٧
Input Capacitance	Cies				4130		pF
Output Capacitance	Coes	V _{CE} =20V, f=1MHz			114		pF
Reverse Transfer Capacitance	Cres	1			96		pF
Turn-ON Delay Time	t _d (on)				100		ns
Rise Time	t _r	V _{CC} =300V, I _C =30A			60		ns
Turn-ON Time	ton				540		ns
Turn-OFF Delay Time	t _d (off)	R _G =30Ω, L=200μH			390		ns
Fall Time	tf	VGE=0V/15V Vclamp=400V See Fig.1, See Fig.2			80		ns
Turn-OFF Time	toff				500		ns
Turn-ON Energy	Eon				0.31		mJ
Turn-OFF Energy	Eoff				1.14		mJ
Turn-ON Delay Time	t _d (on)				98		ns
Rise Time	t _r				85		ns
Turn-ON Time	ton	V _{CC} =300V, I _C =50A			650		ns
Turn-OFF Delay Time	t _d (off)	R _G =30Ω, L=200μH			380		ns
Fall Time	tf	V _{GE} =0V/15V			90		ns
Turn-OFF Time	toff	Vclamp=400V See Fig.1, See Fig.2			530		ns
Turn-ON Energy	Eon				0.638		mJ
Turn-OFF Energy	Eoff				2.755		mJ
Total Gate Charge	Qg	V _{CE} =300V, V _{GE} =15V, I _C =30A			166		nC
Gate to Emitter Charge	Qge				40		nC
Gate to Collector "Miller" Charge	Qgc				70		nC
Diode Reverse Recovery Time	t _{rr}	I _F =10A, di/dt=100A/μs, V _{CC} =50V, See Fig.3			70		ns

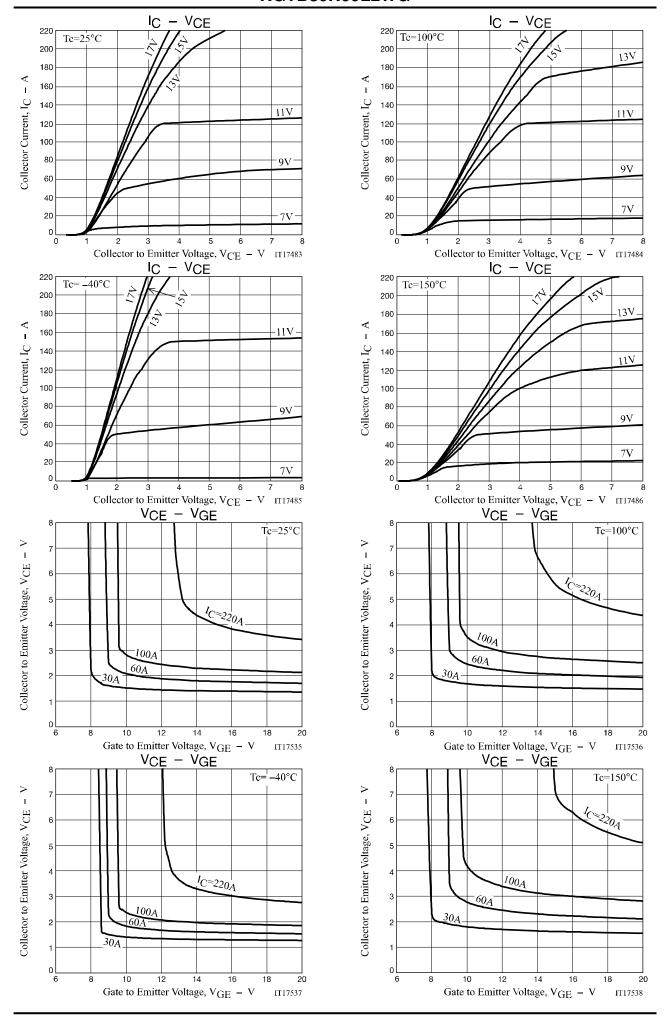
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

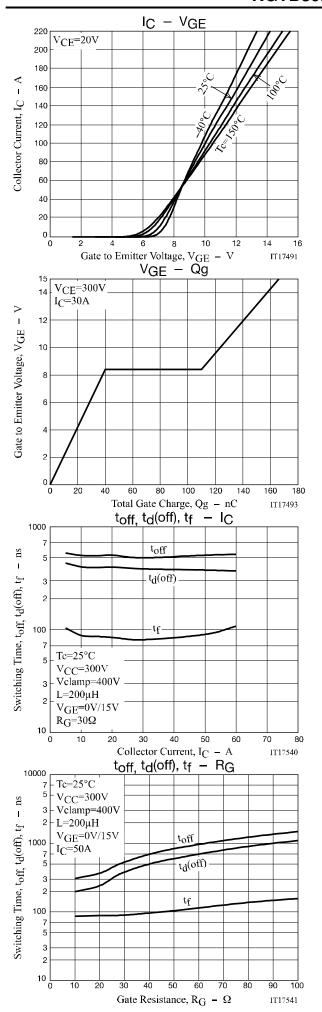
Thermal Characteristics at Ta = 25°C, Unless otherwise specified

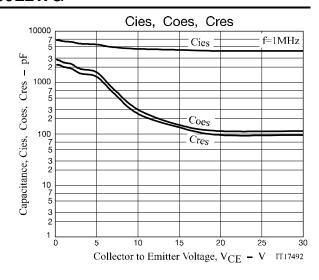
Parameter	Symbol	Conditions	Value	Unit
Thermal Resistance IGBT (Junction to Case)	Rth(j-c) (IGBT)	Tc=25°C (Our ideal heat dissipation condition)*2	0.67	°C /W
Thermal Resistance Diode (Junction to Case)	Rth(j-c) (Diode)	Tc=25°C (Our ideal heat dissipation condition)*2	1.5	°C /W
Thermal Resistance (Junction to Ambient)	Rth(j-a)		41	°C /W

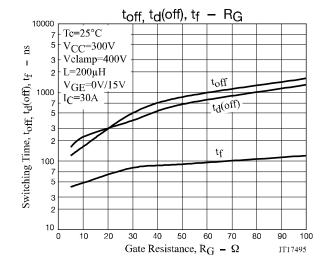
Note: *2 Our condition is radiation from backside.

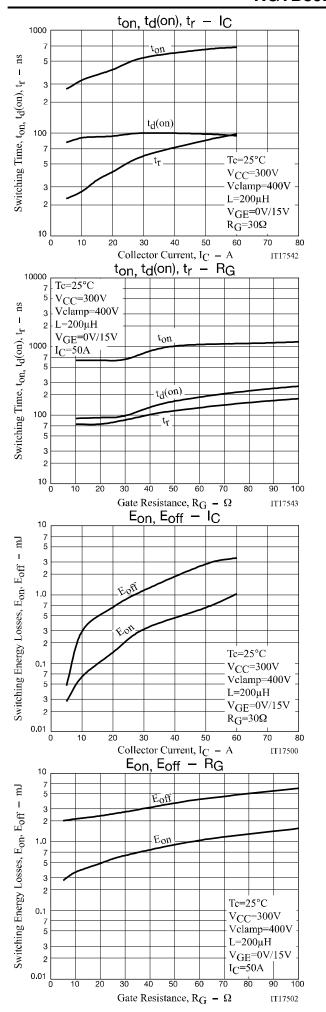
The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.

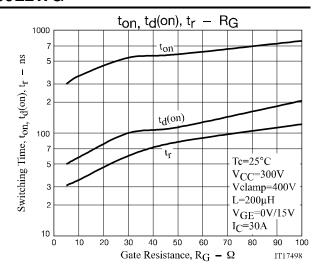


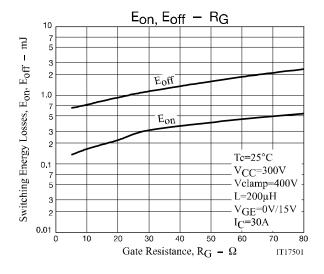


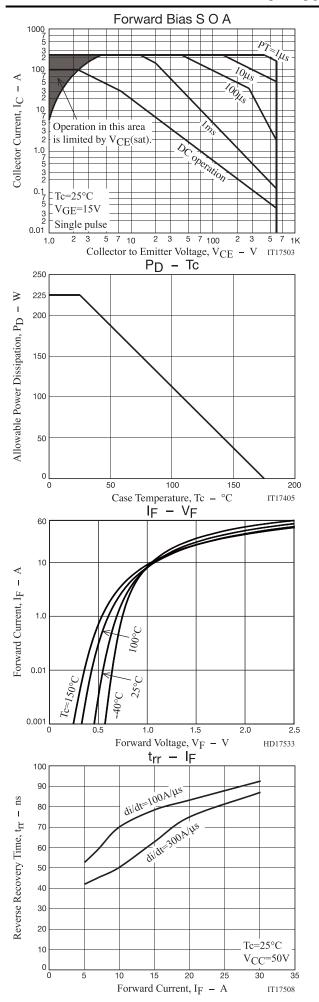


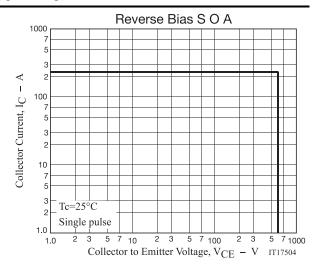


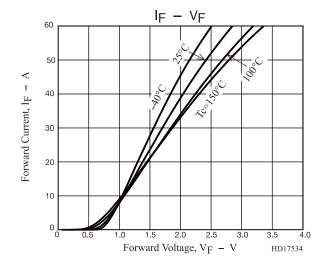












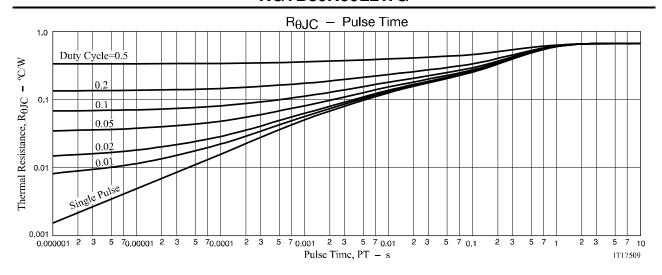


Fig.1 Switching Time Test Circuit

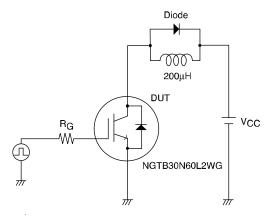


Fig.2 Timing Chart

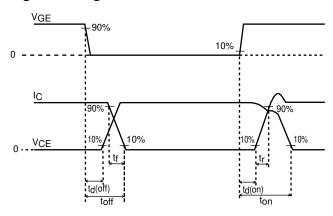
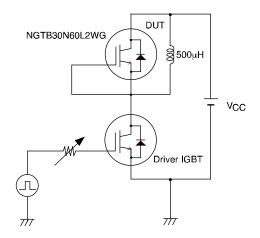


Fig.3 Reverse Recovery Time Test Circuit

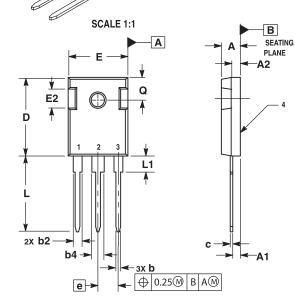


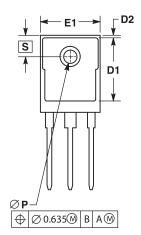
Package Dimensions

NGTB30N60L2WG

TO-247

CASE 340AK **ISSUE O** unit: mm





- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
 SLOT REQUIRED, NOTCH MAY BE ROUNDED.
 THERMAL PAD CONTOUR OPTIONAL WITHIN DIMEN-
- SIONS D1 AND E1.
 LEAD FINISH UNCONTROLLED WITHIN L1.
- $^{\mbox{\it Q}}\mbox{\it P}$ To have a maximum draft angle of 1.5° to the top of the part with a maximum diameter

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	1.00	1.40	0.039	0.055	
b2	1.65	2.39	0.065	0.094	
b4	2.59	3.43	0.102	0.135	
С	0.38	0.89	0.015	0.035	
D	20.80	21.46	0.819	0.845	
D1	13.08		0.515		
D2	0.51	1.35	0.020	0.053	
Е	15.49	16.26	0.610	0.640	
E1	13.46		0.53		
E2	4.32	5.49	0.170	0.216	
е	5.46	5.46 BSC		0.215 BSC	
L	19.81	20.32	0.780	0.800	
L1	-	4.50	-	0.177	
Р	3.56	3.66	0.140	0.144	
Q	5.38	6.20	0.212	0.244	
S	6.15 BSC		0.242 BSC		

Ordering & Package Information

Device	Package	Shipping	note
NGTB30N60L2WG	TO-247-3L	30 pcs. / tube	Pb-Free and Halogen Free

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